

# 74AHC2G08-Q100; 74AHCT2G08-Q100

Dual 2-input AND gate

Rev. 2 — 21 January 2014

Product data sheet

## 1. General description

The 74AHC2G08-Q100 and 74AHCT2G08-Q100 are high-speed Si-gate CMOS devices. They provide two 2-input AND gates.

The AHC device has CMOS input switching levels and supply voltage range 2 V to 5.5 V.

The AHCT device has TTL input switching levels and supply voltage range 4.5 V to 5.5 V.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Symmetrical output impedance
- High noise immunity
- Low power dissipation
- Balanced propagation delays
- Multiple package options
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0  $\Omega$ )

## 3. Ordering information

Table 1. Ordering information

| Type number                           | Package   |        |   |          |
|---------------------------------------|---|--------|---|----------|
|                                       | Temperature range   | Name   | Description   | Version  |
| 74AHC2G08DP-Q100<br>74AHCT2G08DP-Q100 | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | TSSOP8 | plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm | SOT505-2 |
| 74AHC2G08DC-Q100<br>74AHCT2G08DC-Q100 | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | VSSOP8 | plastic very thin shrink small outline package; 8 leads; body width 2.3 mm              | SOT765-1 |



## 4. Marking

Table 2. Marking

| Type number       | Marking code <sup>[1]</sup> |
|-------------------|-----------------------------|
| 74AHC2G08DP-Q100  | A08                         |
| 74AHCT2G08DP-Q100 | C08                         |
| 74AHC2G08DC-Q100  | A08                         |
| 74AHCT2G08DC-Q100 | C08                         |

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

## 5. Functional diagram

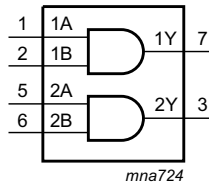


Fig 1. Logic symbol

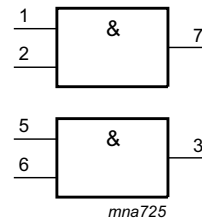


Fig 2. IEC logic symbol

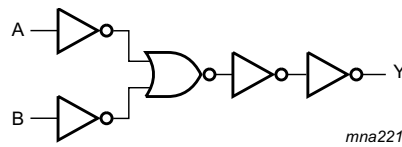


Fig 3. Logic diagram (one gate)

## 6. Pinning information

### 6.1 Pinning

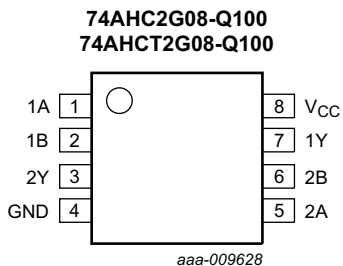


Fig 4. Pin configuration SOT505-2 (TSSOP8) and SOT765-1 (VSSOP8)

### 6.2 Pin description

Table 3. Pin description

| Symbol          | Pin  | Description    |
|-----------------|------|----------------|
| 1A, 2A          | 1, 5 | data input     |
| 1B, 2B          | 2, 6 | data input     |
| GND             | 4    | ground (0 V)   |
| 1Y, 2Y          | 7, 3 | data output    |
| V <sub>CC</sub> | 8    | supply voltage |

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

| Input |    | Output |
|-------|----|--------|
| nA    | nB | nY     |
| L     | L  | L      |
| L     | H  | L      |
| H     | L  | L      |
| H     | H  | H      |

[1] H = HIGH voltage level; L = LOW voltage level.

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol    | Parameter               | Conditions                               | Min     | Max      | Unit |
|-----------|-------------------------|--|---------|----------|------|
| $V_{CC}$  | supply voltage          |  | -0.5    | +7.0     | V    |
| $V_I$     | input voltage           |  | -0.5    | +7.0     | V    |
| $I_{IK}$  | input clamping current  | $V_I < -0.5$ V                           | [1] -20 | -        | mA   |
| $I_{OK}$  | output clamping current | $V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V | [1] -   | $\pm 20$ | mA   |
| $I_O$     | output current          | $-0.5$ V $< V_O < V_{CC} + 0.5$ V        | -       | $\pm 25$ | mA   |
| $I_{CC}$  | supply current          |  | -       | 75       | mA   |
| $I_{GND}$ | ground current          |  | -75     | -        | mA   |
| $T_{stg}$ | storage temperature     |  | -65     | +150     | °C   |
| $P_{tot}$ | total power dissipation | $T_{amb} = -40$ °C to +125 °C            | [2] -   | 250      | mW   |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP8 package: above 55 °C the value of  $P_{tot}$  derates linearly with 2.5 mW/K.  
For VSSOP8 package: above 110 °C the value of  $P_{tot}$  derates linearly with 8 mW/K.

## 9. Recommended operating conditions

**Table 6. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V).

| Symbol              | Parameter                           | Conditions                   | 74AHC2G08-Q100 |     |          | 74AHCT2G08-Q100 |     |          | Unit |
|---------------------|-------------------------------------|------------------------------|----------------|-----|----------|-----------------|-----|----------|------|
|                     |                                     |                              | Min            | Typ | Max      | Min             | Typ | Max      |      |
| $V_{CC}$            | supply voltage                      |                              | 2.0            | 5.0 | 5.5      | 4.5             | 5.0 | 5.5      | V    |
| $V_I$               | input voltage                       |                              | 0              | -   | 5.5      | 0               | -   | 5.5      | V    |
| $V_O$               | output voltage                      |                              | 0              | -   | $V_{CC}$ | 0               | -   | $V_{CC}$ | V    |
| $T_{amb}$           | ambient temperature                 |                              | -40            | +25 | +125     | -40             | +25 | +125     | °C   |
| $\Delta t/\Delta V$ | input transition rise and fall rate | $V_{CC} = 3.3$ V $\pm 0.3$ V | -              | -   | 100      | -               | -   | -        | ns/V |
|                     |                                     | $V_{CC} = 5.0$ V $\pm 0.5$ V | -              | -   | 20       | -               | -   | 20       | ns/V |

## 10. Static characteristics

**Table 7. Static characteristics**

Voltages are referenced to GND (ground = 0 V).

| Symbol                | Parameter                | Conditions       | 25 °C |     |      | -40 °C to +85 °C |      | -40 °C to +125 °C |      | Unit |
|-----------------------|--------------------------|------------------|-------|-----|------|------------------|------|-------------------|------|------|
|                       |                          |                  | Min   | Typ | Max  | Min              | Max  | Min               | Max  |      |
| <b>74AHC2G08-Q100</b> |                          |                  |       |     |      |                  |      |                   |      |      |
| $V_{IH}$              | HIGH-level input voltage | $V_{CC} = 2.0$ V | 1.5   | -   | -    | 1.5              | -    | 1.5               | -    | V    |
|                       |                          | $V_{CC} = 3.0$ V | 2.1   | -   | -    | 2.1              | -    | 2.1               | -    | V    |
|                       |                          | $V_{CC} = 5.5$ V | 3.85  | -   | -    | 3.85             | -    | 3.85              | -    | V    |
| $V_{IL}$              | LOW-level input voltage  | $V_{CC} = 2.0$ V | -     | -   | 0.5  | -                | 0.5  | -                 | 0.5  | V    |
|                       |                          | $V_{CC} = 3.0$ V | -     | -   | 0.9  | -                | 0.9  | -                 | 0.9  | V    |
|                       |                          | $V_{CC} = 5.5$ V | -     | -   | 1.65 | -                | 1.65 | -                 | 1.65 | V    |

**Table 7. Static characteristics ...continued**  
 Voltages are referenced to GND (ground = 0 V).

| Symbol                 | Parameter                 | Conditions   | 25 °C |     |      | -40 °C to +85 °C |      | -40 °C to +125 °C |      | Unit |
|------------------------|---------------------------|--|-------|-----|------|------------------|------|-------------------|------|------|
|                        |                           |  | Min   | Typ | Max  | Min              | Max  | Min               | Max  |      |
| V <sub>OH</sub>        | HIGH-level output voltage | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>  |       |     |      |                  |      |                   |      |      |
|                        |                           | I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 2.0 V   | 1.9   | 2.0 | -    | 1.9              | -    | 1.9               | -    | V    |
|                        |                           | I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 3.0 V   | 2.9   | 3.0 | -    | 2.9              | -    | 2.9               | -    | V    |
|                        |                           | I <sub>O</sub> = -50 μA; V <sub>CC</sub> = 4.5 V   | 4.4   | 4.5 | -    | 4.4              | -    | 4.4               | -    | V    |
|                        |                           | I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 3.0 V  | 2.58  | -   | -    | 2.48             | -    | 2.40              | -    | V    |
|                        |                           | I <sub>O</sub> = -8.0 mA; V <sub>CC</sub> = 4.5 V  | 3.94  | -   | -    | 3.8              | -    | 3.70              | -    | V    |
| V <sub>OL</sub>        | LOW-level output voltage  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>  |       |     |      |                  |      |                   |      |      |
|                        |                           | I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 2.0 V  | -     | 0   | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
|                        |                           | I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 3.0 V  | -     | 0   | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
|                        |                           | I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 4.5 V  | -     | 0   | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
|                        |                           | I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V   | -     | -   | 0.36 | -                | 0.44 | -                 | 0.55 | V    |
|                        |                           | I <sub>O</sub> = 8.0 mA; V <sub>CC</sub> = 4.5 V   | -     | -   | 0.36 | -                | 0.44 | -                 | 0.55 | V    |
| I <sub>I</sub>         | input leakage current     | V <sub>I</sub> = 5.5 V or GND;<br>V <sub>CC</sub> = 0 V to 5.5 V   | -     | -   | 0.1  | -                | 1.0  | -                 | 2.0  | μA   |
| I <sub>CC</sub>        | supply current            | V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A;<br>V <sub>CC</sub> = 5.5 V  | -     | -   | 1.0  | -                | 10   | -                 | 40   | μA   |
| C <sub>I</sub>         | input capacitance         |  | -     | 1.5 | 10   | -                | 10   | -                 | 10   | pF   |
| <b>74AHCT2G08-Q100</b> |                           |  |       |     |      |                  |      |                   |      |      |
| V <sub>IH</sub>        | HIGH-level input voltage  | V <sub>CC</sub> = 4.5 V to 5.5 V   | 2.0   | -   | -    | 2.0              | -    | 2.0               | -    | V    |
| V <sub>IL</sub>        | LOW-level input voltage   | V <sub>CC</sub> = 4.5 V to 5.5 V   | -     | -   | 0.8  | -                | 0.8  | -                 | 0.8  | V    |
| V <sub>OH</sub>        | HIGH-level output voltage | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V  |       |     |      |                  |      |                   |      |      |
|                        |                           | I <sub>O</sub> = -50 μA  | 4.4   | 4.5 | -    | 4.4              | -    | 4.4               | -    | V    |
|                        |                           | I <sub>O</sub> = -8.0 mA   | 3.94  | -   | -    | 3.8              | -    | 3.70              | -    | V    |
| V <sub>OL</sub>        | LOW-level output voltage  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V  |       |     |      |                  |      |                   |      |      |
|                        |                           | I <sub>O</sub> = 50 μA   | -     | 0   | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
|                        |                           | I <sub>O</sub> = 8.0 mA  | -     | -   | 0.36 | -                | 0.44 | -                 | 0.55 | V    |
| I <sub>I</sub>         | input leakage current     | V <sub>I</sub> = 5.5 V or GND;<br>V <sub>CC</sub> = 0 V to 5.5 V   | -     | -   | 0.1  | -                | 1.0  | -                 | 2.0  | μA   |
| I <sub>CC</sub>        | supply current            | V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A;<br>V <sub>CC</sub> = 5.5 V  | -     | -   | 1.0  | -                | 10   | -                 | 40   | μA   |
| ΔI <sub>CC</sub>       | additional supply current | per input pin; V <sub>I</sub> = 3.4 V;<br>other inputs at V <sub>CC</sub> or GND;<br>I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V | -     | -   | 1.35 | -                | 1.5  | -                 | 1.5  | mA   |
| C <sub>I</sub>         | input capacitance         |  | -     | 1.5 | 10   | -                | 10   | -                 | 10   | pF   |

## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**

GND = 0 V; for test circuit see [Figure 6](#).

| Symbol                 | Parameter                     | Conditions  | 25 °C               |     |      | -40 °C to +85 °C |      | -40 °C to +125 °C |      | Unit |
|------------------------|-------------------------------|---|---------------------|-----|------|------------------|------|-------------------|------|------|
|                        |                               |   | Min                 | Typ | Max  | Min              | Max  | Min               | Max  |      |
| <b>74AHC2G08-Q100</b>  |                               |   |                     |     |      |                  |      |                   |      |      |
| t <sub>pd</sub>        | propagation delay             | nA, nB to nY; see <a href="#">Figure 5</a> <a href="#">[1]</a>                                      |                     |     |      |                  |      |                   |      |      |
|                        |                               | V <sub>CC</sub> = 3.0 V to 3.6 V <a href="#">[2]</a>  |                     |     |      |                  |      |                   |      |      |
|                        |                               | C <sub>L</sub> = 15 pF  | -                   | 4.6 | 8.8  | 1.0              | 10.5 | 1.0               | 12.0 | ns   |
|                        |                               | C <sub>L</sub> = 50 pF  | -                   | 6.5 | 12.3 | 1.0              | 14.0 | 1.0               | 16.0 | ns   |
|                        |                               | V <sub>CC</sub> = 4.5 V to 5.5 V <a href="#">[3]</a>  |                     |     |      |                  |      |                   |      |      |
|                        |                               | C <sub>L</sub> = 15 pF  | -                   | 3.2 | 5.9  | 1.0              | 7.0  | 1.0               | 8.0  | ns   |
|                        |                               | C <sub>L</sub> = 50 pF  | -                   | 4.6 | 7.9  | 1.0              | 9.0  | 1.0               | 10.5 | ns   |
| C <sub>PD</sub>        | power dissipation capacitance | per buffer; C <sub>L</sub> = 50 pF; f <sub>i</sub> = 1 MHz; V <sub>i</sub> = GND to V <sub>CC</sub> | <a href="#">[4]</a> | -   | 17   | -                | -    | -                 | -    | pF   |
| <b>74AHCT2G08-Q100</b> |                               |   |                     |     |      |                  |      |                   |      |      |
| t <sub>pd</sub>        | propagation delay             | nA, nB to nY; see <a href="#">Figure 5</a> <a href="#">[1]</a>                                      |                     |     |      |                  |      |                   |      |      |
|                        |                               | V <sub>CC</sub> = 4.5 V to 5.5 V <a href="#">[3]</a>  |                     |     |      |                  |      |                   |      |      |
|                        |                               | C <sub>L</sub> = 15 pF  | -                   | 3.6 | 6.2  | 1.0              | 7.1  | 1.0               | 8.0  | ns   |
|                        |                               | C <sub>L</sub> = 50 pF  | -                   | 5.1 | 7.9  | 1.0              | 9.0  | 1.0               | 10.5 | ns   |
| C <sub>PD</sub>        | power dissipation capacitance | per buffer; C <sub>L</sub> = 50 pF; f <sub>i</sub> = 1 MHz; V <sub>i</sub> = GND to V <sub>CC</sub> | <a href="#">[4]</a> | -   | 19   | -                | -    | -                 | -    | pF   |

[1] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.

[2] Typical values are measured at V<sub>CC</sub> = 3.3 V.

[3] Typical values are measured at V<sub>CC</sub> = 5.0 V.

[4] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

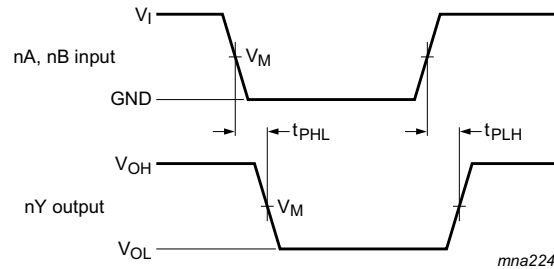
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs.

## 12. Waveforms



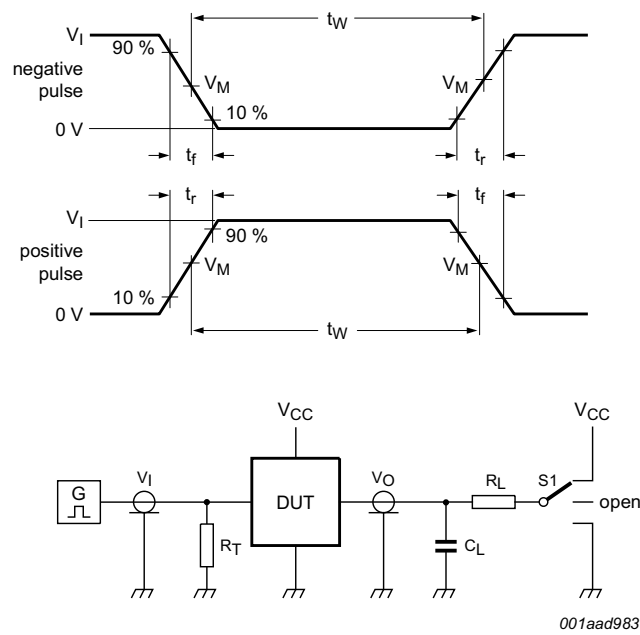
Measurement points are given in [Table 9](#).

Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 5. The input (nA and nB) to output (nY) propagation delays**

**Table 9. Measurement points**

| Type            | Input       | Output      |
|-----------------|-------------|-------------|
|                 | $V_M$       | $V_M$       |
| 74AHC2G08-Q100  | $0.5V_{CC}$ | $0.5V_{CC}$ |
| 74AHCT2G08-Q100 | 1.5 V       | $0.5V_{CC}$ |



Test data is given in [Table 10](#).

Definitions test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_L$  = Load resistance.

S1 = Test selection switch.

**Fig 6. Test circuit for measuring switching times**

**Table 10. Test data**

| Type            | Input    |             | Load         |              | S1 position        |
|-----------------|----------|-------------|--------------|--------------|--------------------|
|                 | $V_I$    | $t_r, t_f$  | $C_L$        | $R_L$        | $t_{PHL}, t_{PLH}$ |
| 74AHC2G08-Q100  | $V_{CC}$ | $\leq 3$ ns | 15 pF, 50 pF | 1 k $\Omega$ | open               |
| 74AHCT2G08-Q100 | 3 V      | $\leq 3$ ns | 15 pF, 50 pF | 1 k $\Omega$ | open               |



### 13. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2

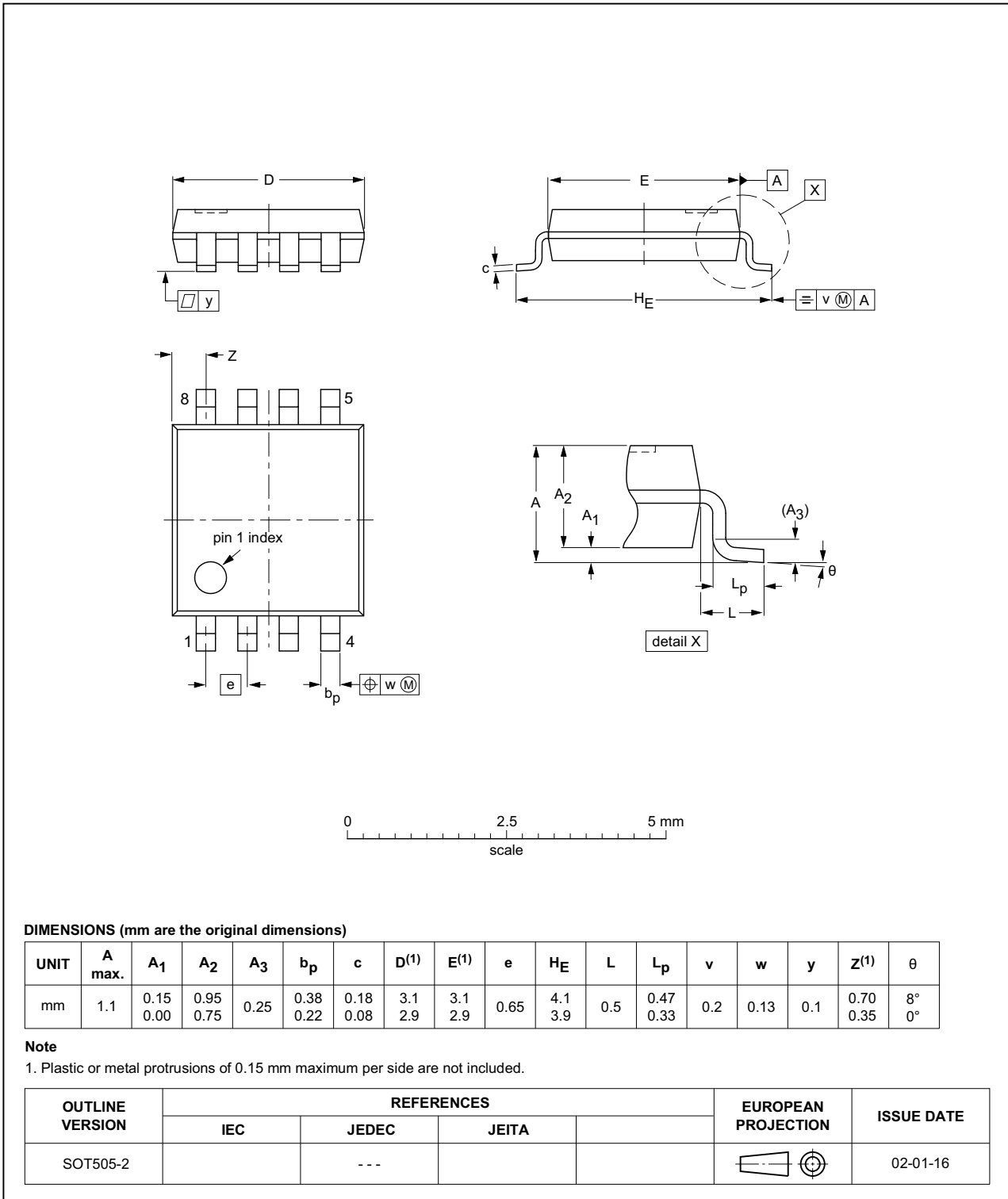


Fig 7. Package outline SOT505-2 (TSSOP8)

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1

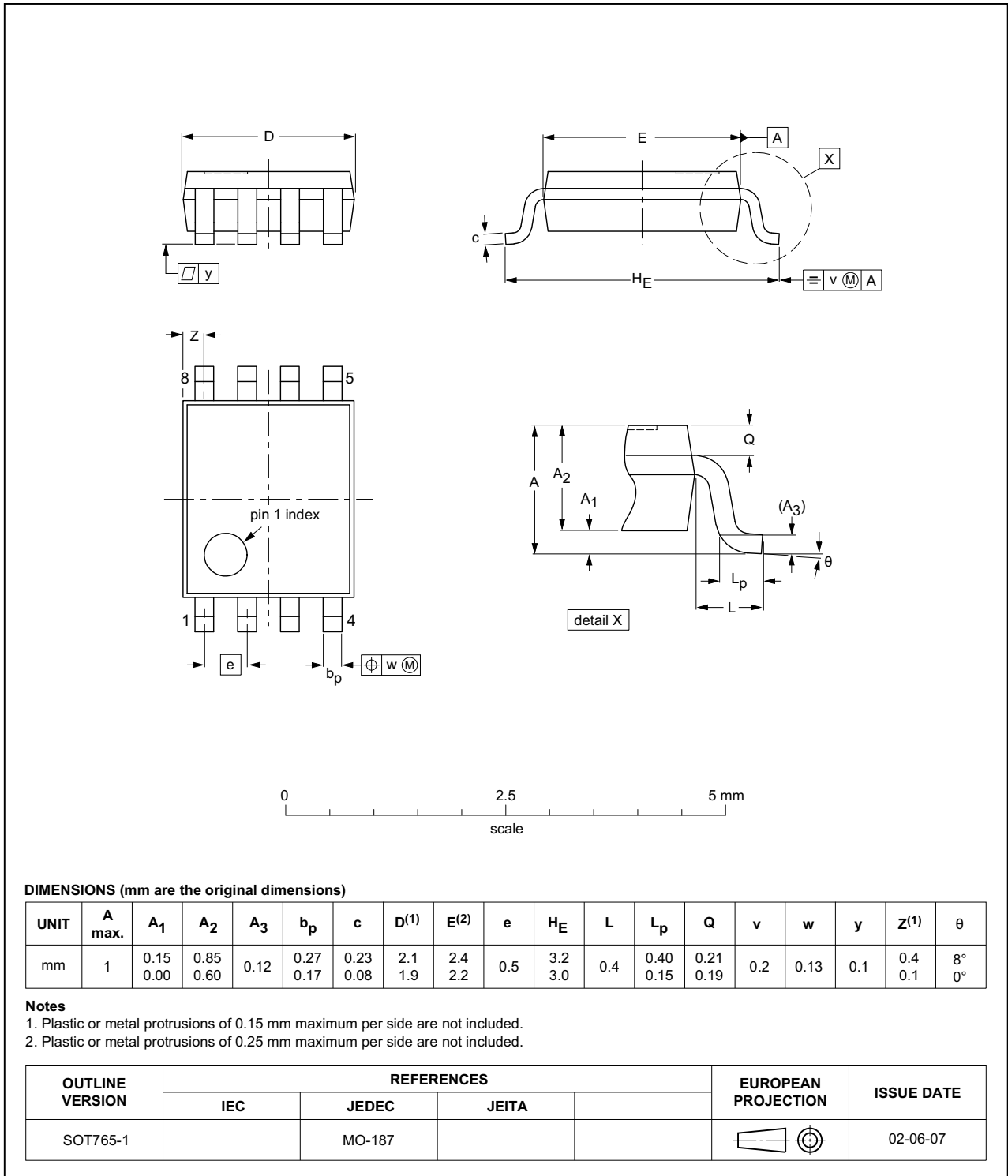


Fig 8. Package outline SOT765-1 (VSSOP8)

## 14. Abbreviations

Table 11. Abbreviations

| Acronym | Description                             |
|---------|---|
| CDM     | Charged Device Model                    |
| CMOS    | Complementary Metal-Oxide Semiconductor |
| DUT     | Device Under Test                       |
| ESD     | ElectroStatic Discharge                 |
| HBM     | Human Body Model                        |
| MIL     | Military                                |
| MM      | Machine Model                           |
| TTL     | Transistor-Transistor Logic             |

## 15. Revision history

Table 12. Revision history

| Document ID             | Release date                            | Data sheet status  | Change notice | Supersedes              |
|-------------------------|---|--------------------|---------------|-------------------------|
| 74AHC_AHCT2G08_Q100 v.2 | 20140121                                | Product data sheet | -             | 74AHC_AHCT2G08_Q100 v.1 |
| Modifications:          | • General description updated (errata). |                    |               |                         |
| 74AHC_AHCT2G08_Q100 v.1 | 20131113                                | Product data sheet | -             | -                       |

## 16. Legal information

### 16.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

### 16.2 Definitions

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## 18. Contents

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|      |  |    |
|------|--|----|
| 1    | General description . . . . .              | 1  |
| 2    | Features and benefits . . . . .            | 1  |
| 3    | Ordering information . . . . .             | 1  |
| 4    | Marking . . . . .                          | 2  |
| 5    | Functional diagram . . . . .               | 2  |
| 6    | Pinning information . . . . .              | 3  |
| 6.1  | Pinning . . . . .                          | 3  |
| 6.2  | Pin description . . . . .                  | 3  |
| 7    | Functional description . . . . .           | 3  |
| 8    | Limiting values . . . . .                  | 4  |
| 9    | Recommended operating conditions . . . . . | 4  |
| 10   | Static characteristics . . . . .           | 4  |
| 11   | Dynamic characteristics . . . . .          | 6  |
| 12   | Waveforms . . . . .                        | 7  |
| 13   | Package outline . . . . .                  | 9  |
| 14   | Abbreviations . . . . .                    | 11 |
| 15   | Revision history . . . . .                 | 11 |
| 16   | Legal information . . . . .                | 12 |
| 16.1 | Data sheet status . . . . .                | 12 |
| 16.2 | Definitions . . . . .                      | 12 |
| 16.3 | Disclaimers . . . . .                      | 12 |
| 16.4 | Trademarks . . . . .                       | 13 |
| 17   | Contact information . . . . .              | 13 |
| 18   | Contents . . . . .                         | 14 |

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